



PGA206 PGA207

High-Speed Programmable Gain INSTRUMENTATION AMPLIFIER

FEATURES

 DIGITALLY PROGRAMMABLE GAINS: PGA206: G=1, 2, 4, 8V/V

PGA200: G=1, 2, 4, 6V/V PGA207: G=1, 2, 5, 10V/V

• TRUE INSTRUMENTATION AMP INPUT

● FAST SETTLING: 3.5µs to 0.01%

FET INPUT: I_B = 100pA max
 INPUT PROTECTION: ±40V

● LOW OFFSET VOLTAGE: 1.5mV max

• 16-PIN DIP, SOL-16 SOIC PACKAGES

APPLICATIONS

- MULTIPLE-CHANNEL DATA ACQUISITION
- MEDICAL, PHYSIOLOGICAL AMPLIFIER
- PC-CONTROLLED ANALOG INPUT BOARDS

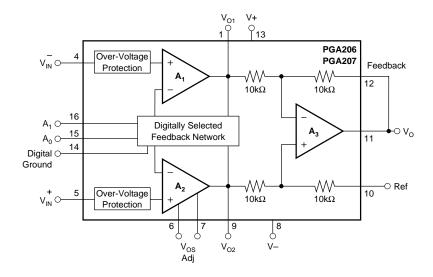
DESCRIPTION

The PGA206 and PGA207 are digitally programmable gain instrumentation amplifiers that are ideally suited for data acquisition systems.

The PGA206 and PGA207's fast settling time allows multiplexed input channels for excellent system efficiency. FET inputs eliminate $I_{\rm B}$ errors due to analog multiplexer series resistance.

Gains are selected by two CMOS/TTL-compatible address lines. Analog inputs are internally protected for overloads up to $\pm40V$, even with the power supplies off. The PGA206 and PGA207 are laser-trimmed for low offset voltage and low drift.

The PGA206 and PGA207 are available in 16-pin plastic DIP and SOL-16 surface-mount packages. Both are specified for -40°C to +85°C operation.



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SPECIFICATIONS

At T_A = +25°C, V_S = ±15V, R_L = 2k Ω unless otherwise noted.

			PGA206P, U PGA207P, U		l .	PGA206PA, U PGA207PA, U		
PARAMETER	CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
INPUT Offset Voltage, RTI	All Gains							
Initial vs Temperature 1	I $T_A = +25^{\circ}C$ $I_A = T_{MIN}$ to T_{MAX} , $G = 8$, 10) 1	±0.5 ±2	±1.5		±1 *	±2.5	mV μV/°C
vs Power Supply	$V_{S} = \pm 4.5 \text{V to } \pm 18 \text{V}$		±5	±20		±10	±40	μV/V
Long-Term Stability	, and the second		4.5			*		μV/mo
Impedance, Differential Common-Mode			10 ¹³ 1 10 ¹² 4			*		$\Omega \parallel pF$ $\Omega \parallel pF$
Common-Mode Voltage Range ⁽¹⁾	V _O = 0V	±(V _S -4)	±(V _S -2.5)		*	*		V
Safe Input Voltage	Ü	(1 01)	, ,	±40			*	V
Common-Mode Rejection	$V_{CM} = \pm 11V$, $\Delta R_S = 1k\Omega$ G = 1	80	92		75	86		dB
	G = 2	85	96		80	90		dB
	G = 4 or 5	90	100		84	94		dB
	G = 8 or 10	95	100		84	94		dB
INPUT BIAS CURRENT	V _{IN} = 0		2	100		*	*	pA
vs Temperature Offset Current		Se	ee Typical Cun 1	/e 100		*	*	pA
vs Temperature		Se	ee Typical Cur			*	7	PA
NOISE VOLTAGE, RTI	$G = 8,10; R_S = 0\Omega$							
f = 10Hz			30			*		nV/√ <u>Hz</u>
f = 100Hz			20			*		nV/√Hz
f = 1kHz $f_R = 0.1Hz$ to 10Hz			18 1			*		nV/√Hz μVp-p
Noise Current								' ' '
f = 1kHz			1.5			*		fA/√Hz
GAIN	All Gains, V _O = ±11V							
Gain Error Gain vs Temperature ⁽²⁾			±0.01 ±1	±0.05 ±10		*	±0.1 *	% ppm/°C
Nonlinearity			±0.0003	±0.002		*	±0.005	% of FSR
OUTPUT								
Voltage, Positive		(V+) -4	(V+) -2.3		*	*		V
Negative Load Capacitance Stability		(V–) +4	(V-) +1.5 1000		*	*		V pF
Short-Circuit Current			±17			*		mA
FREQUENCY RESPONSE								
Bandwidth, -3dB	G = 1		5			*		MHz
	G = 2		4			*		MHz
	G = 4, 5 G = 8, 10		1.3 600			*		MHz kHz
Slew Rate	$V_0 = \pm 10V$, G = 1 to 10		25			*		V/μs
Settling Time, 0.1%	20V Step, All Gains		2			*		μs
0.01% Output Overload Recovery	20V Step, All Gains 50% Overdrive		3.5 1.5			*		μs μs
DIGITAL LOGIC INPUTS	0070 000141100		1.0					μο
Digital Ground Voltage, V _{DG}		V–		(V+) -4	*		*	V
Digital Low Voltage		V-		V _{DG} + 0.8V	*		*	V
Digital Input Current Digital High Voltage		\/ .2	1	V+	*	*	V-	pA V
Gain Switching Time		V _{DG} +2	500	V+	*	*	*	ns
POWER SUPPLY							1	
Voltage Range		±4.5	±15	±18	*	*	*	V
Current	V _{IN} = 0V		+12.4/–11.2	±13.5		*		mA
TEMPERATURE RANGE		40		. 65	٠.		ļ	
Specification Operating		-40 -40		+85 +125	*		*	°C

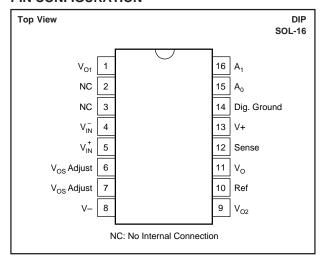
 $[\]ensuremath{\boldsymbol{\ast}}$ Specification same as PGA206P or PGA207P.

NOTES: (1) Input common-mode range varies with output voltage—see typical curves. (2) Guaranteed by wafer test.

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PIN CONFIGURATION



PACKAGE INFORMATION

PRODUCT	PACKAGE	PACKAGE DRAWING NUMBER ⁽¹⁾
PGA206PA	16-Pin Plastic DIP	180
PGA206P	16-Pin Plastic DIP	180
PGA206UA	SOL-16 Surface Mount	211
PGA206U	SOL-16 Surface Mount	211
PGA207PA	16-Pin Plastic DIP	180
PGA207P	16-Pin Plastic DIP	180
PGA207UA	SOL-16 Surface Mount	211
PGA207U	SOL-16 Surface Mount	211

NOTE: (1) For detailed drawing and dimension table, please see end of data sheet, or Appendix C of Burr-Brown IC Data Book.

ABSOLUTE MAXIMUM RATINGS

Supply Voltage	±18V
Analog Input Voltage Range	
Logic Input Voltage Range	±V _S
Output Short-Circuit (to ground)	Continuous
Operating Temperature	40°C to +125°C
Storage Temperature	40°C to +125°C
Junction Temperature	+150°C
Lead Temperature (soldering -10s)	+300°C

ORDERING INFORMATION

PRODUCT	GAINS	PACKAGE	TEMPERATURE RANGE
PGA206PA	1, 2, 4, 8V/V	16-Pin Plastic DIP	-40°C to +85°C
PGA206P	1, 2, 4, 8V/V	16-Pin Plastic DIP	-40°C to +85°C
PGA206UA	1, 2, 4, 8V/V	SOL-16 Surface-Mount	-40°C to +85°C
PGA206U	1, 2, 4, 8V/V	SOL-16 Surface-Mount	-40°C to +85°C
PGA207PA	1, 2, 5, 10V/V	16-Pin Plastic DIP	-40°C to +85°C
PGA207P	1, 2, 5, 10V/V	16-Pin Plastic DIP	-40°C to +85°C
PGA207UA	1, 2, 5, 10V/V	SOL-16 Surface-Mount	-40°C to +85°C
PGA207U	1, 2, 5, 10V/V	SOL-16 Surface-Mount	-40°C to +85°C

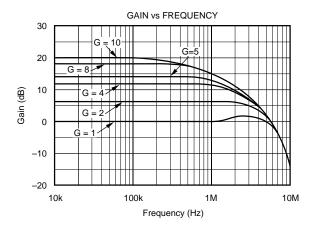


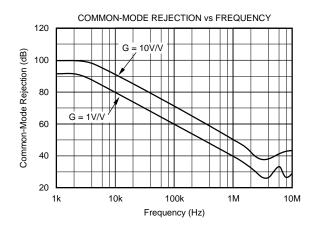
This integrated circuit can be damaged by ESD. Burr-Brown recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

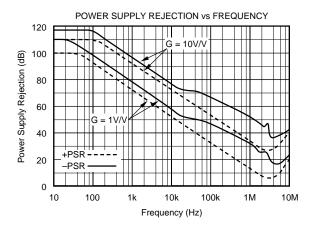
ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

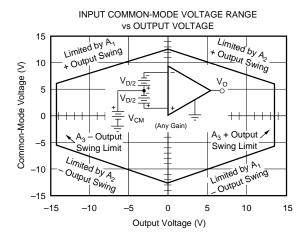
TYPICAL PERFORMANCE CURVES

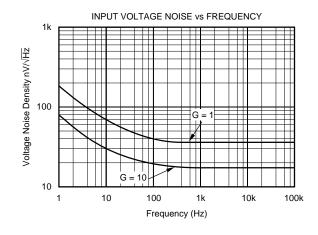
At T_A = +25°C, and V_S = ±15V, unless otherwise noted.

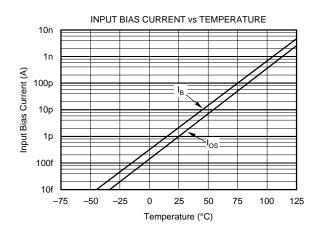








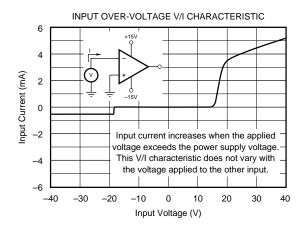


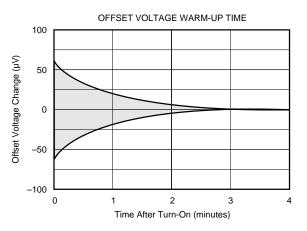


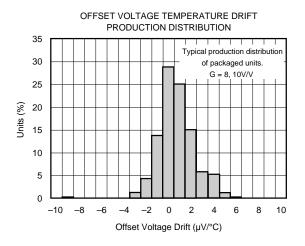


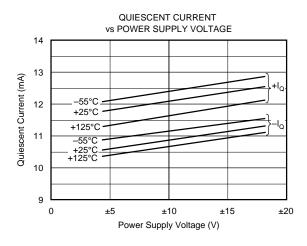
TYPICAL PERFORMANCE CURVES (CONT)

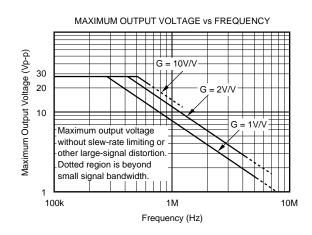
At T_A = +25°C, and V_S = ±15V, unless otherwise noted.

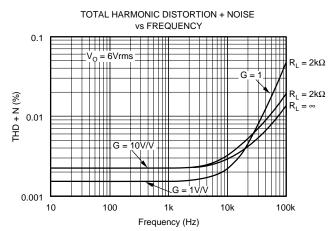






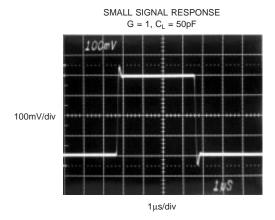


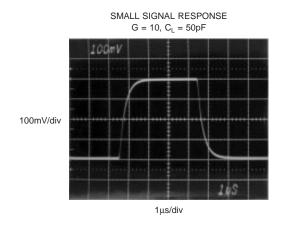


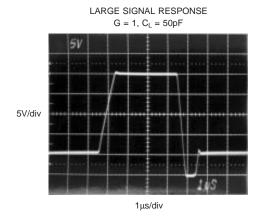


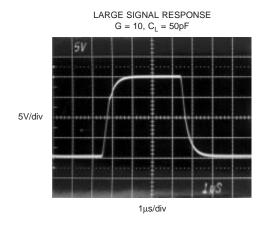
TYPICAL PERFORMANCE CURVES (CONT)

At T_A = +25°C, and V_S = ±15V, unless otherwise noted.









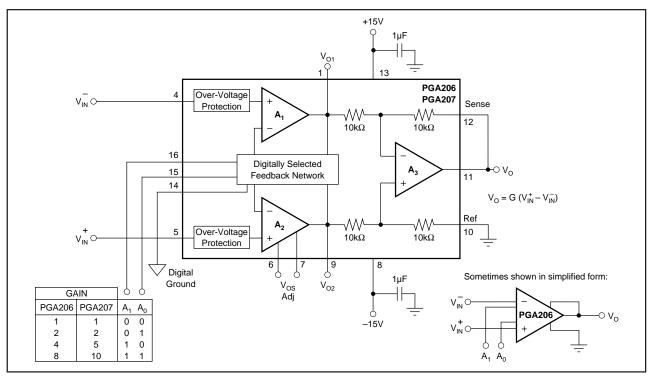


FIGURE 1. Basic Connections.

APPLICATIONS INFORMATION

Figure 1 shows the circuit diagram for basic operation of the PGA206 or PGA207. Applications with noisy or high impedance power supplies may require decoupling capacitors close to the device pins as shown.

The output is referred to the output reference (Ref) terminal which is normally grounded. This must be a low-impedance connection to assure good common-mode rejection. A resistance of 2Ω in series with the Ref pin will cause a typical device to degrade to approximately 80dB CMR (G = 1).

The output sense connection (pin 12) must be connected to the output terminal (pin 11) for proper operation. This connection can be made at the load for best accuracy.

DIGITAL INPUTS

The digital inputs A_0 and A_1 select the gain according to the logic table in Figure 1. Logic "1" is defined as a voltage greater than 2V above digital ground potential (pin 14). Digital ground can be connected to any potential ranging from the V– power supply to 4V less than V+. Digital ground is usually equal to analog ground potential and the two grounds are connected at the power supply. The digital inputs interface directly to CMOS and TTL logic.

A nearly constant current of approximately 1.2mA flows in the digital ground pin. It is good practice to return digital ground through a separate connection path so that analog ground is not affected by the digital ground current. The digital inputs, A_0 and A_1 , are not latched. A change in logic input immediately selects a new gain. Switching time of the logic is approximately 500ns. The time to respond to gain change is equal to switching time, plus the time it takes the amplifier to settle to a new output voltage in the newly selected gain (see settling time specifications).

Many applications use an external logic latch to acquire gain control data from a high speed digital bus. Using an external latch isolates the high speed digital bus from sensitive analog circuitry. Locate the digital latch as far as practical from analog circuitry to avoid coupling digital noise into analog input circuitry.

OFFSET VOLTAGE ADJUSTMENT

The PGA206 and PGA207 are laser trimmed for very low offset voltage and drift. Many applications require no external offset adjustment. Multiplexed data acquisition systems generally correct offset by grounding the inputs of one channel to measure offset voltage. Stored offset values for each gain are then subtracted from subsequent readings of other channels.

Figure 2 shows optional offset voltage trim circuits. Offset voltage changes with the selected gain. To adjust for low offset voltage in all gains, both input and output offsets must be trimmed.

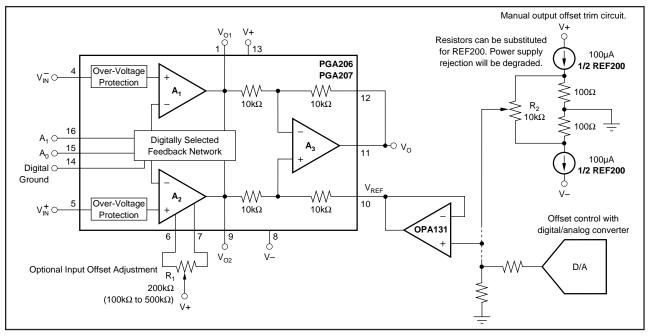


FIGURE 2. Optional Offset Voltage Trim Circuits.

 R_1 adjusts the offset of the input amplifiers. Output stage offset is adjusted with $R_2.\ A$ buffer op amp is required in the output offset adjustment circuit, as shown, to assure that the Ref pin is driven by a low source impedance. To adjust for low offset voltage in all gains, first adjust the input stage offset in the highest gain. Then adjust the output stage offset (R_2) in G=1. Iterate the adjustments for lowest offset in all gains.

Offset can also be adjusted under processor control with a D/A converter as shown in Figure 2. The D/A's output voltage can be reduced with a resistor divider for better adjustment resolution, but an op amp buffer following the divider is required to provide a low source impedance to the ref terminal. A different offset value is required for each amplifier gain.

INPUT BIAS CURRENT RETURN PATH

The FET inputs of the PGA206 and PGA207 provide extremely high input impedance. Still, a path must be provided for the bias current of each input. Figure 3 shows provisions for an input bias current path. Without a bias current return path, the inputs will float to a potential which exceeds the linear input voltage range and the input amplifiers will saturate.

If the differential source resistance is low, a bias current return path can be connected to only one input (see thermocouple example in Figure 3). With higher source impedance, using two resistors provides a balanced input with possible advantages of lower input offset voltage due to bias current and better common-mode rejection.

Many sources or sensors inherently provide a path for input bias current (e.g. the bridge sensor shown in Figure 3). These applications do not require additional resistor(s) for proper operation.

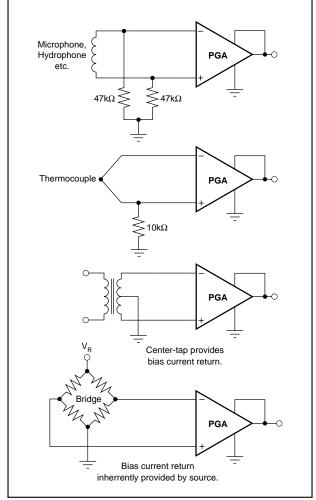


FIGURE 3. Providing an Input Bias Current Path.



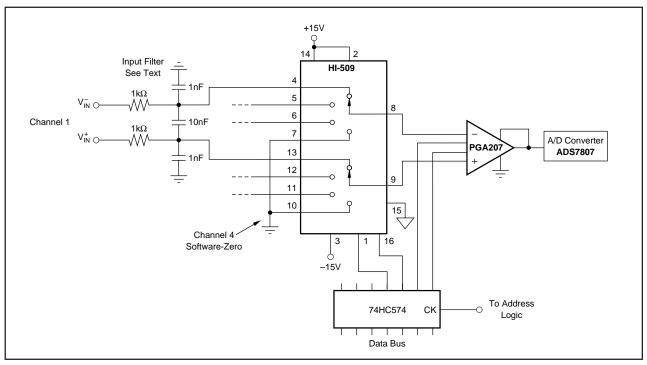


FIGURE 4. Multiplexed-Input Signal Acquisition System.

INPUT COMMON-MODE RANGE

The linear input voltage range of the PGA206 and PGA207 is from approximately 2.3V below the positive supply voltage to 1.5V above the negative supply. As a differential input voltage causes output voltage to increase, however, the linear input range is limited by the output voltage swing of amplifiers A_1 and A_2 . So the linear common-mode input range is related to the output voltage of the complete amplifier. This behavior also depends on supply voltage—see performance curves "Input Common-Mode Range vs Output Voltage".

Input overload can produce an output voltage that appears normal. For example, if an input overload condition drives both input amplifiers to their positive output swing limit, the difference voltage measured by the output amplifier will be near zero. The output of the PGA206 or PGA207 will be near 0V even though both inputs are overloaded. This condition can be detected by sensing the voltage on the V_{01} and V_{02} pins to determine whether they are within their linear operating range.

INPUT PROTECTION

The inputs of the PGA206 and PGA207 are individually protected for voltages up to ± 40 V. For example, a condition of -40V on one input and +40V on the other input will not cause damage. Internal circuitry on each input provides low series impedance under normal signal conditions. If the input is overloaded, the protection circuitry limits the input current to a safe value. The typical performance curve "Input Overload V/I Characteristic" shows this behavior. The inputs are protected even if no power supply voltage is applied.

MULTIPLEXED INPUTS

The PGA206 and PGA207 are ideally suited for multiple channel data acquisition. Figure 4 shows a typical application with an analog multiplexer used to connect one of four differential input signals to a single PGA207.

Careful circuit layout will help preserve accuracy of multiplexed signals. Run the inverting and non-inverting connections of each channel parallel to each other over a ground plane, or directly adjacent on top and bottom of the circuit board. Grounded guard traces between channels help reduce stray signal pick-up.

Multiplexed signals from high impedance sources require special care. As inputs are switched by the multiplexer, charge can be injected into the source, disturbing the input signal. Since many such sources involve slow signals, a simple R/C filter at the input can be used to dramatically reduce this effect. The arrangement shown filters both the differential signal and common-mode noise.

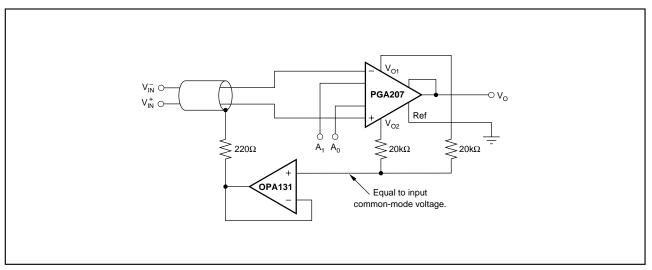


FIGURE 5. Shield Drive Circuit.

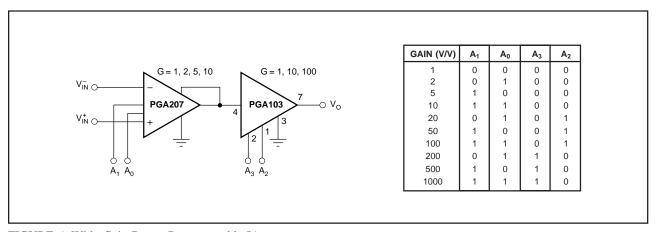


FIGURE 6. Wide Gain Range Programmable IA.





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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
PGA206PA	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
PGA206PAG4	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
PGA206UA	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
PGA206UAG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
PGA207PA	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
PGA207UA	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
PGA207UA/1K	ACTIVE	SOIC	DW	16	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
PGA207UA/1KE4	ACTIVE	SOIC	DW	16	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
PGA207UAE4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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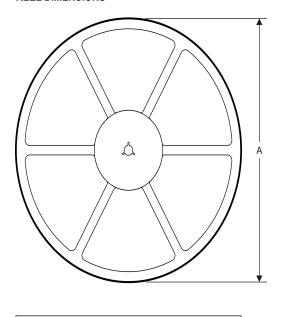
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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
PGA207UA/1K	SOIC	DW	16	1000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

www.ti.com 14-Jul-2012



*All dimensions are nominal

I	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
I	PGA207UA/1K	SOIC	DW	16	1000	367.0	367.0	38.0

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